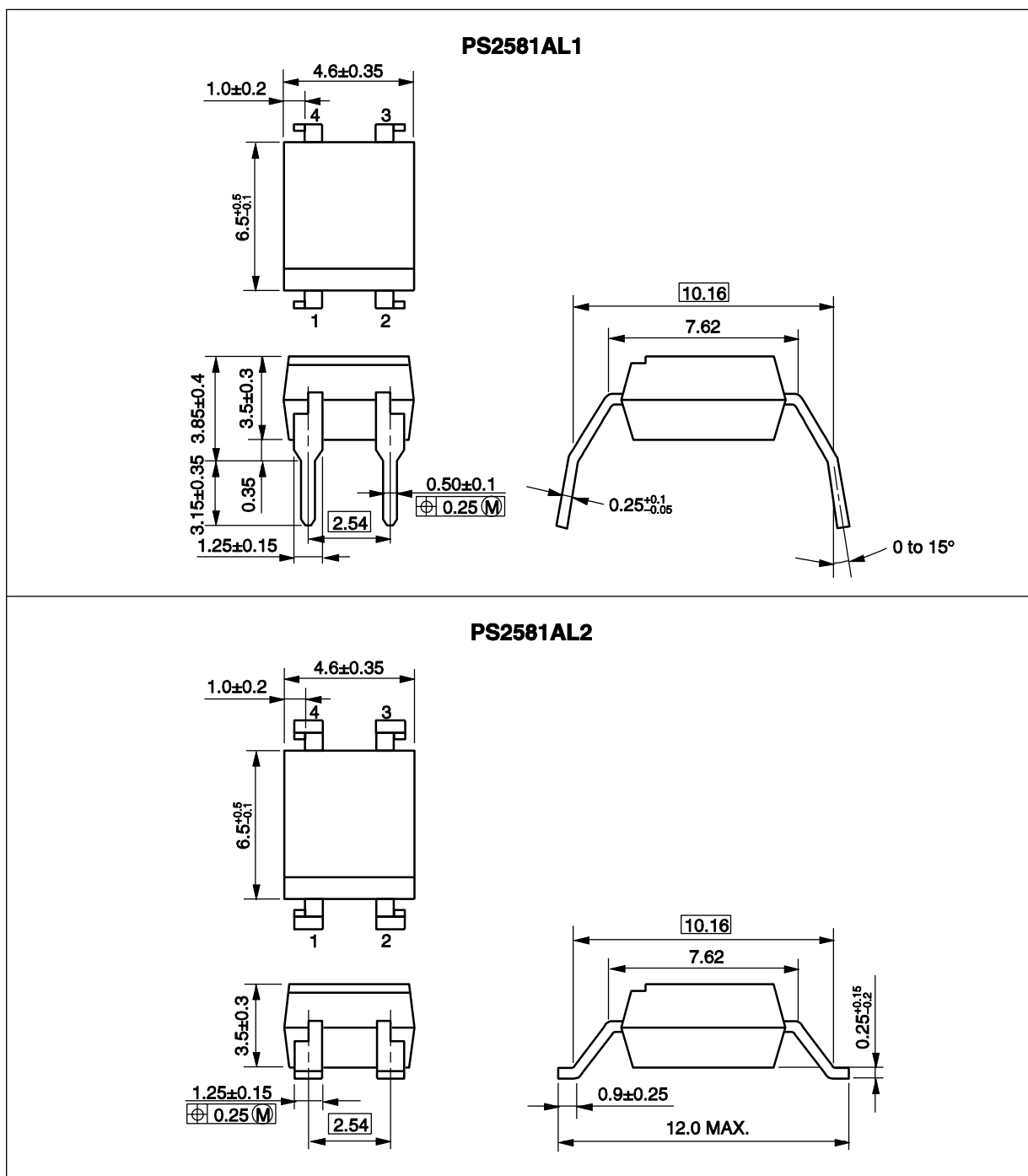


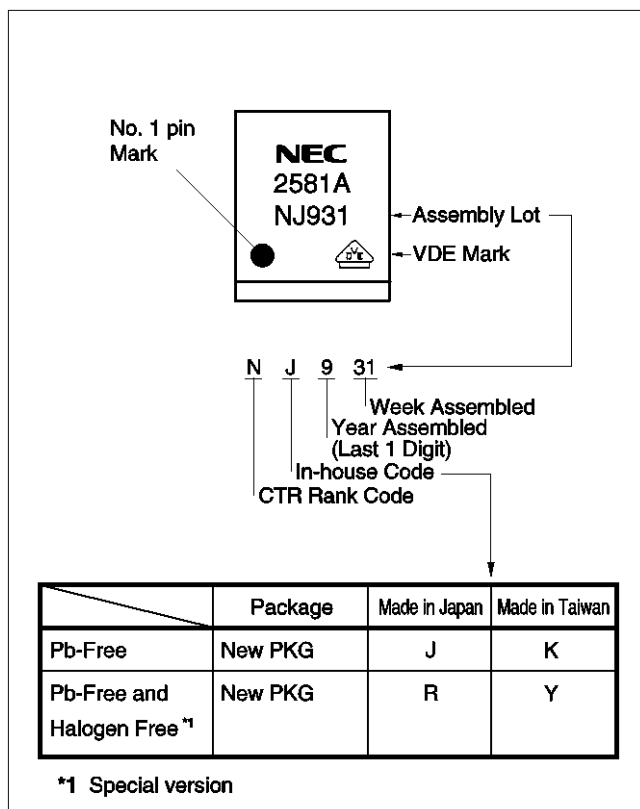
PACKAGE DIMENSIONS (UNIT : mm)



PHOTOCOUPLER CONSTRUCTION

Parameter	Unit (MIN.)
Air Distance	8 mm
Outer Creepage Distance	8 mm
Inner Creepage Distance	4 mm
Isolation Thickness	0.4 mm

<R> MARKING EXAMPLE



ORDERING INFORMATION

Part Number	Order Number	Solder Plating Specification	Packing Style	Safety Standard Approval	Application Part Number ^{*1}		
PS2581AL1	PS2581AL1-A	Pb-Free	Magazine case 100 pcs	Standard products (UL, CSA, BSI, NEMKO, SEMKO, DEMKO, FIMKO, DIN EN60747-5-2 (VDE0884 Part2) Approved products)	PS2581AL1		
PS2581AL2	PS2581AL2-A		Embossed Tape 1 000 pcs/reel			PS2581AL2	
PS2581AL2-E3	PS2581AL2-E3-A						
PS2581AL2-E4	PS2581AL2-E4-A						
PS2581AL1	PS2581AL1-Y-A	Special version	Magazine case 100 pcs		PS2581AL1		
PS2581AL2	PS2581AL2-Y-A	(Pb-Free and	Embossed Tape 1 000 pcs/reel			PS2581AL2	
PS2581AL2-E3	PS2581AL2-Y-E3-A	Halogen Free)					

***1** For the application of the Safety Standard, following part number should be used.

ABSOLUTE MAXIMUM RATINGS (T_A = 25°C, unless otherwise specified)

Parameter		Symbol	Ratings	Unit
Diode	Reverse Voltage	V _R	6	V
	Forward Current (DC)	I _F	30	mA
	Power Dissipation Derating	ΔP _D /°C	1.5	mW/°C
	Power Dissipation	P _D	150	mW
	Peak Forward Current ^{*1}	I _{FP}	0.5	A
Transistor	Collector to Emitter Voltage	V _{CEO}	70	V
	Emitter to Collector Voltage	V _{ECO}	5	V
	Collector Current	I _C	30	mA
	Power Dissipation Delay	ΔP _C /°C	1.5	mW/°C
	Power Dissipation	P _C	150	mW
Isolation Voltage ^{*2}		BV	5 000	Vr.m.s.
Operating Ambient Temperature		T _A	-55 to +100	°C
Storage Temperature		T _{stg}	-55 to +150	°C

***1** PW = 100 μs, Duty Cycle = 1%

***2** AC voltage for 1 minute at T_A = 25°C, RH = 60% between input and output
Pins 1-2 shorted together, 3-4 shorted together.

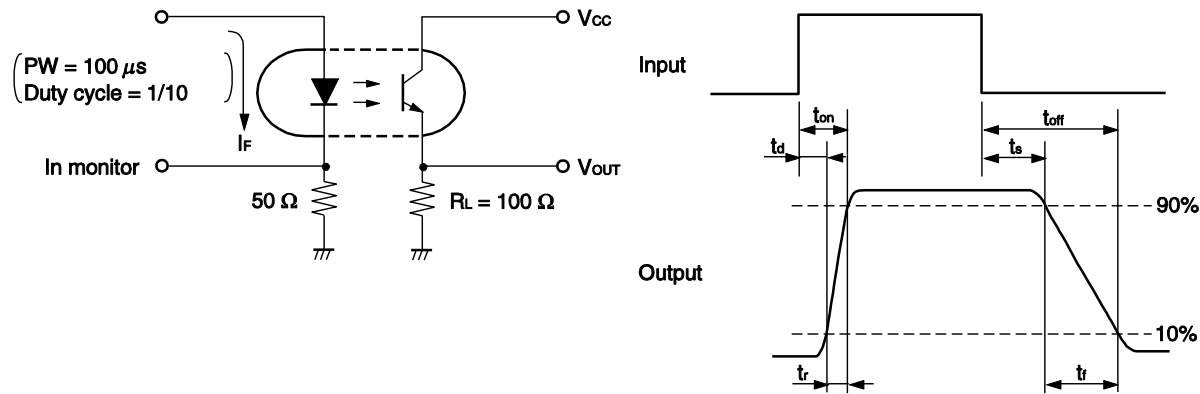
ELECTRICAL CHARACTERISTICS (T_A = 25°C)

Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Diode	Forward Voltage	V _F	I _F = 10 mA		1.2	1.4	V
	Reverse Current	I _R	V _R = 5 V			5	μA
	Terminal Capacitance	C _t	V = 0 V, f = 1.0 MHz		10		pF
Transistor	Collector to Emitter Dark Current	I _{CEO}	V _{CE} = 70 V, I _F = 0 mA			100	nA
Coupled	Current Transfer Ratio (I _c /I _F)* ¹	CTR	I _F = 5 mA, V _{CE} = 5 V	50		400	%
	Collector Saturation Voltage	V _{CE(sat)}	I _F = 10 mA, I _c = 2 mA		0.13	0.3	V
	Isolation Resistance	R _{I-O}	V _{I-O} = 1.0 kV _{DC}	10 ¹¹			Ω
	Isolation Capacitance	C _{I-O}	V = 0 V, f = 1.0 MHz		0.4		pF
	Rise Time* ²	t _r	V _{CC} = 10 V, I _c = 2 mA, R _L = 100 Ω		3		μs
	Fall Time* ²	t _f			5		

*1 CTR rank

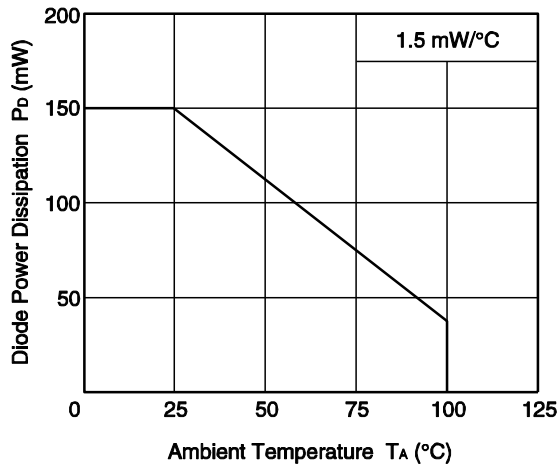
- N : 50 to 400 (%)
H : 80 to 160 (%)
Q : 100 to 200 (%)
W : 130 to 260 (%)
L : 200 to 400 (%)

*2 Test circuit for switching time

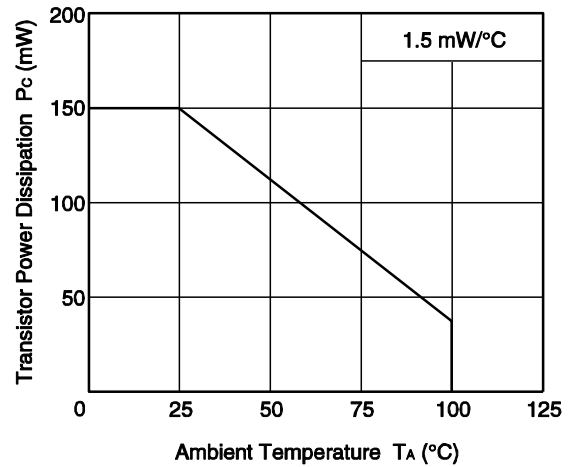


<R> TYPICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$, unless otherwise specified)

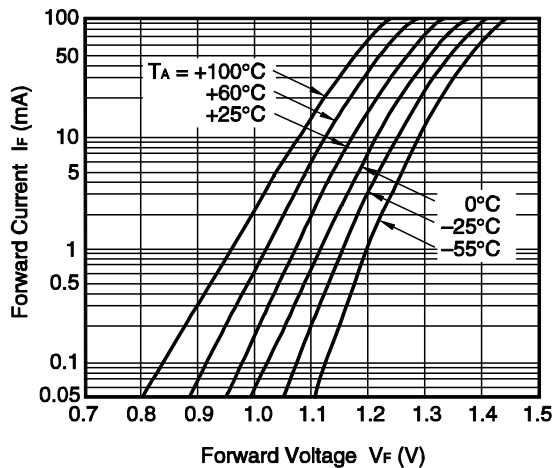
DIODE POWER DISSIPATION vs.
AMBIENT TEMPERATURE



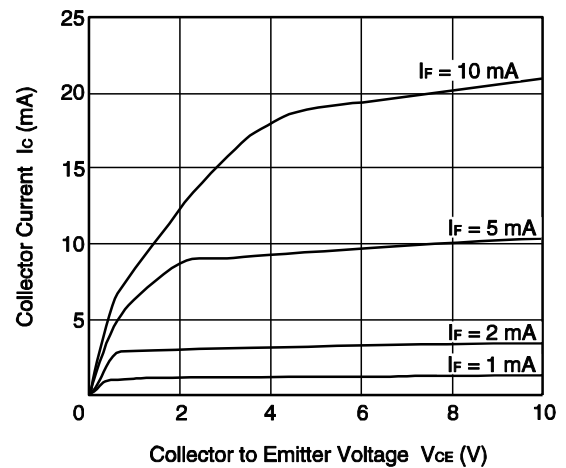
TRANSISTOR POWER DISSIPATION
vs. AMBIENT TEMPERATURE



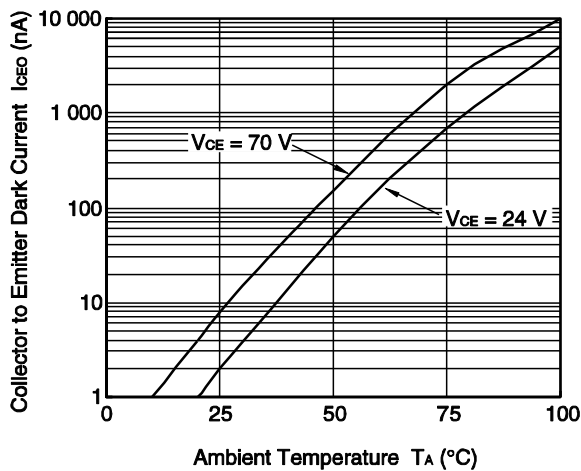
FORWARD CURRENT vs.
FORWARD VOLTAGE



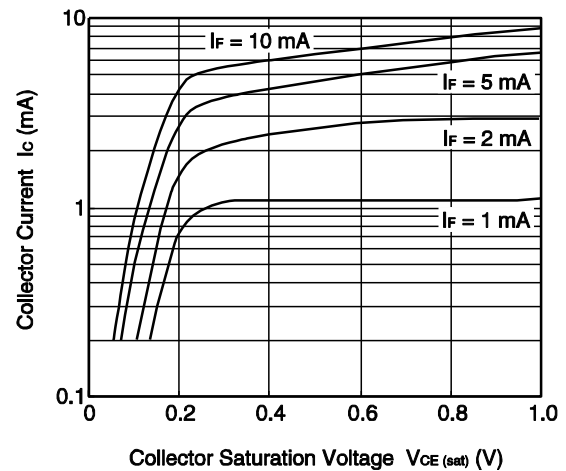
COLLECTOR CURRENT vs.
COLLECTOR TO EMITTER VOLTAGE



COLLECTOR TO EMITTER DARK
CURRENT vs. AMBIENT TEMPERATURE

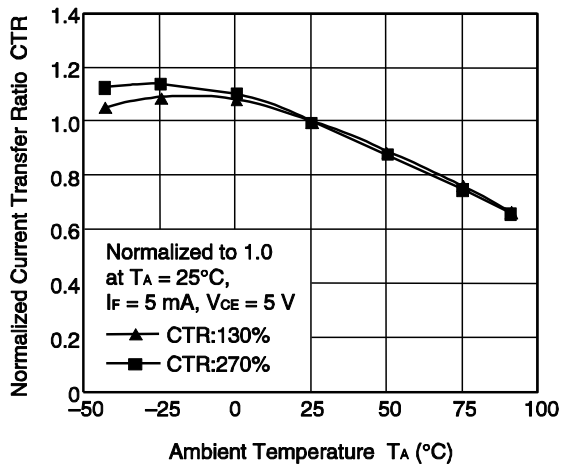


COLLECTOR CURRENT vs.
COLLECTOR SATURATION VOLTAGE

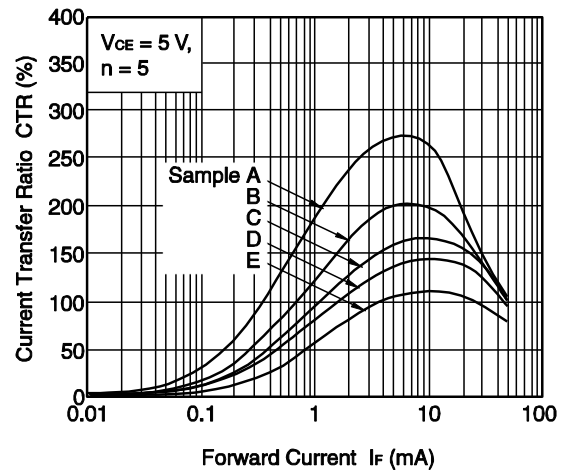


Remark The graphs indicate nominal characteristics.

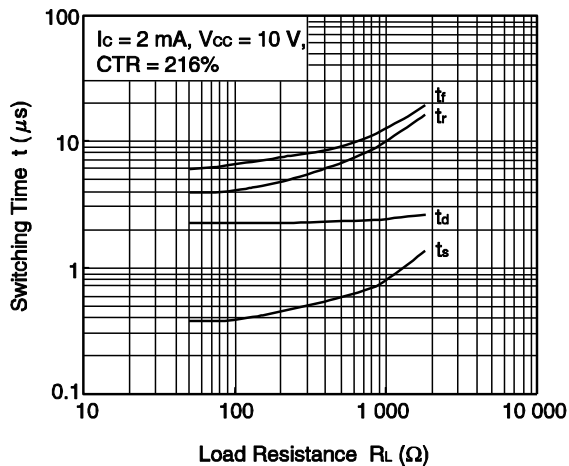
NORMALIZED CURRENT TRANSFER RATIO vs. AMBIENT TEMPERATURE



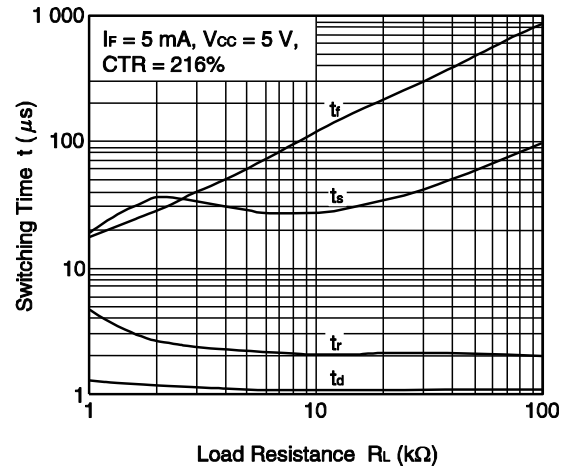
CURRENT TRANSFER RATIO vs. FORWARD CURRENT



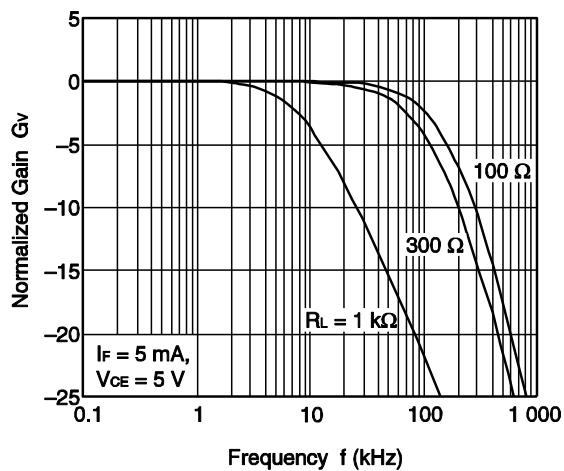
SWITCHING TIME vs. LOAD RESISTANCE



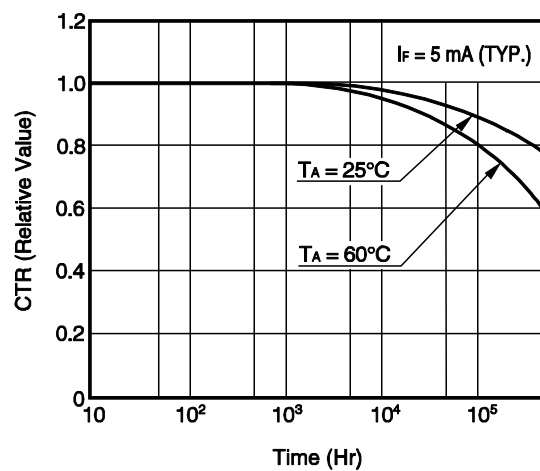
SWITCHING TIME vs. LOAD RESISTANCE



FREQUENCY RESPONSE



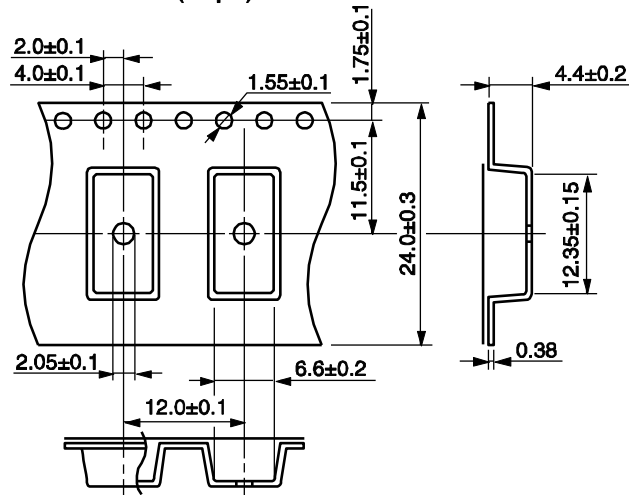
LONG TERM CTR DEGRADATION



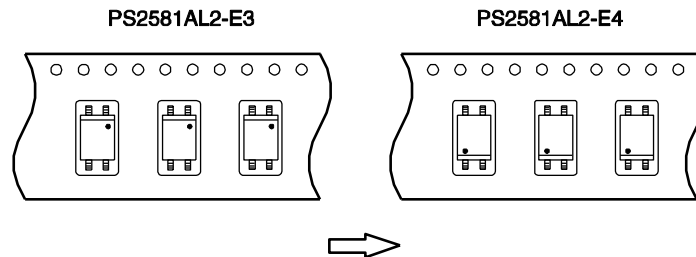
Remark The graphs indicate nominal characteristics.

TAPING SPECIFICATIONS (UNIT : mm)

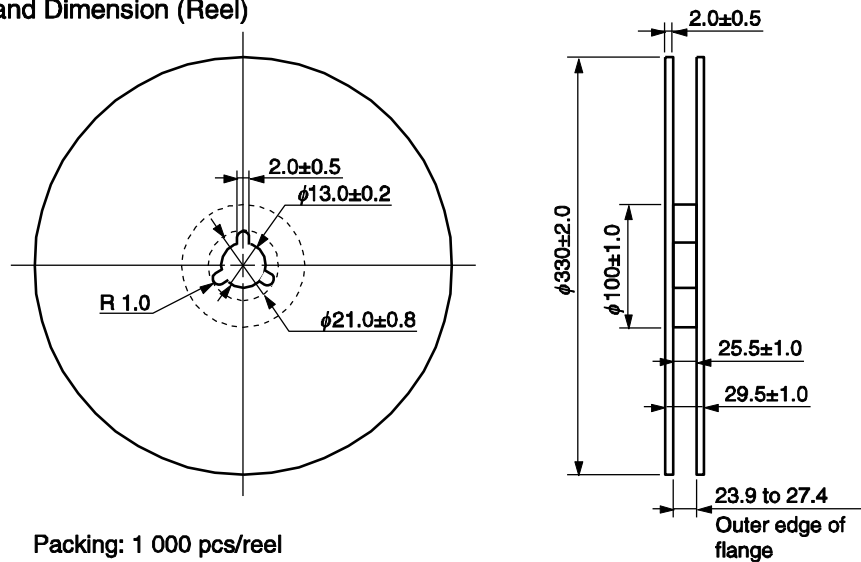
Outline and Dimensions (Tape)



Tape Direction



Outline and Dimension (Reel)



Packing: 1 000 pcs/reel

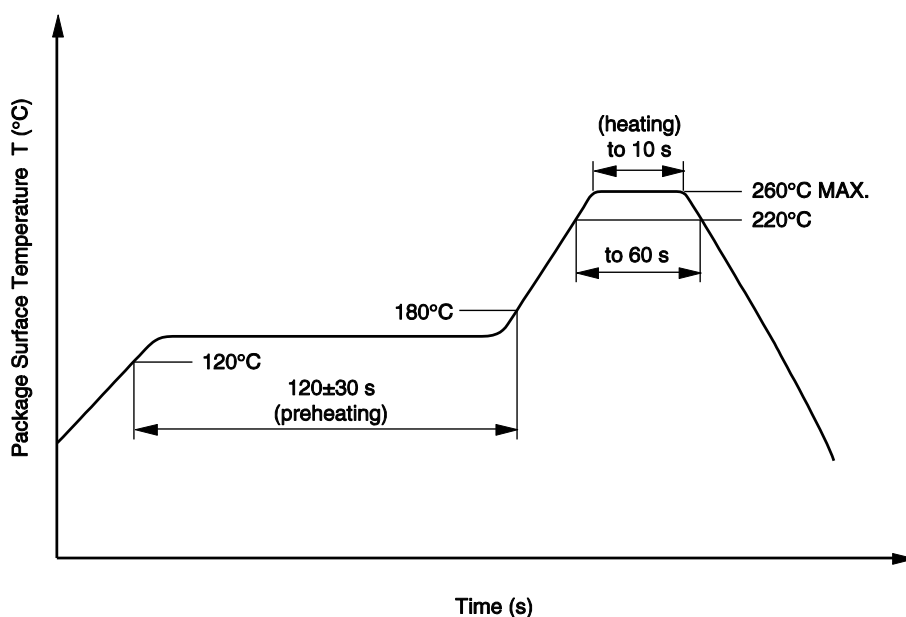
NOTES ON HANDLING

1. Recommended soldering conditions

(1) Infrared reflow soldering

- Peak reflow temperature 260°C or below (package surface temperature)
- Time of peak reflow temperature 10 seconds or less
- Time of temperature higher than 220°C 60 seconds or less
- Time to preheat temperature from 120 to 180°C 120±30 s
- Number of reflows Three
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

Recommended Temperature Profile of Infrared Reflow



(2) Wave soldering

- Temperature 260°C or below (molten solder temperature)
- Time 10 seconds or less
- Preheating conditions 120°C or below (package surface temperature)
- Number of times One (Allowed to be dipped in solder including plastic mold portion.)
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

(3) Soldering by soldering iron

- Peak temperature (lead part temperature) 350°C or below
- Time (each pins) 3 seconds or less
- Flux Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

(a) Soldering of leads should be made at the point 1.5 to 2.0 mm from the root of the lead.

(b) Please be sure that the temperature of the package would not be heated over 100°C.

(4) Cautions

- Fluxes

Avoid removing the residual flux with freon-based and chlorine-based cleaning solvent.

2. Cautions regarding noise

Be aware that when voltage is applied suddenly between the photocoupler's input and output or between collector-emitters at startup, the output transistor may enter the on state, even if the voltage is within the absolute maximum ratings.

3. Measurement conditions of current transfer ratios (CTR), which differ according to photocoupler

Check the setting values before use, since the forward current conditions at CTR measurement differ according to product.

When using products other than at the specified forward current, the characteristics curves may differ from the standard curves due to CTR value variations or the like. This tendency may sometimes be obvious, especially below $I_F = 1$ mA.

Therefore, check the characteristics under the actual operating conditions and thoroughly take variations or the like into consideration before use.

USAGE CAUTIONS

1. Protect against static electricity when handling.
2. Avoid storage at a high temperature and high humidity.

<R> SPECIFICATION OF VDE MARKS LICENSE DOCUMENT

Parameter	Symbol	Spec.	Unit
Climatic test class (IEC 60068-1/DIN EN 60068-1)		55/100/21	
Dielectric strength maximum operating isolation voltage Test voltage (partial discharge test, procedure a for type test and random test) $U_{pr} = 1.5 \times U_{IORM}$, $P_d < 5 \text{ pC}$	U_{IORM} U_{pr}	1 130 1 695	V_{peak} V_{peak}
Test voltage (partial discharge test, procedure b for all devices) $U_{pr} = 1.875 \times U_{IORM}$, $P_d < 5 \text{ pC}$	U_{pr}	1 669	V_{peak}
Highest permissible overvoltage	U_{TR}	8 000	V_{peak}
Degree of pollution (DIN EN 60664-1 VDE0110 Part 1)		2	
Comparative tracking index (IEC 60112/DIN EN 60112 (VDE 0303 Part 11))	CTI	175	
Material group (DIN EN 60664-1 VDE0110 Part 1)		III a	
Storage temperature range	T_{stg}	-55 to +150	°C
Operating temperature range	T_A	-55 to +100	°C
Isolation resistance, minimum value $V_{IO} = 500 \text{ V dc}$ at $T_A = 25^\circ\text{C}$ $V_{IO} = 500 \text{ V dc}$ at $T_A \text{ MAX.}$ at least 100°C	$R_{is \text{ MIN.}}$ $R_{is \text{ MIN.}}$	10^{12} 10^{11}	Ω Ω
Safety maximum ratings (maximum permissible in case of fault, see thermal derating curve) Package temperature Current (input current I_F , $P_{si} = 0$) Power (output or total power dissipation) Isolation resistance $V_{IO} = 500 \text{ V dc}$ at $T_A = T_{si}$	T_{si} I_{si} P_{si} $R_{is \text{ MIN.}}$	175 400 700 10^9	°C mA mW Ω

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M8E0904E

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